



Dow Electronic Materials Wins New Product Introduction Award

AUROLECTROLESS™ SMT 520 Immersion Gold Bath Wins Best New Product in Final Finish Category from Printed Circuit Design & Fabrication Magazine

High-performance and cost-effective solution to be showcased at the Circuitex Suzhou Show

SHANGHAI, CHINA – May 10, 2011 – [Dow Electronic Materials](#), a business of The Dow Chemical Company (NYSE:DOW), recently received the New Product Introduction (NPI) Award from Printed Circuit Design & Fabrication (PCD&F) Magazine for its [AUROLECTROLESS™ SMT 520 Immersion Gold Bath](#) solution in the Final Finish category for printed circuit board (PCB) manufacturing. To address the concern for rising raw material costs, the enhanced-performance bath offers cost benefits by consuming less precious metal. The company will give a presentation titled “A Novel Immersion Gold for Electroless Nickel Immersion Gold (ENIG) Process in PCB Application” and showcase the bath with other innovative solutions at the upcoming Circuitex Suzhou Show.

“The new bath from Dow Electronic Materials, which permits operation at low gold salt concentrations to reduce gold consumption in ENIG processes, was seen as the most innovative in the Final Finish category.” said Mike Buetow, editor-in-chief of PCD&F. [AUROLECTROLESS™ SMT 520 Immersion Gold Bath](#) is a new Final Finish bath providing solderability, wire bonding and corrosion protection. The bath provides excellent deposit coverage to increase corrosion resistance during subsequent process steps. The NPI Award, in its fourth year, recognizes the leading new products during the past 12 months. Awards are selected by an independent panel of practicing industry engineers.

“Dow Electronic Materials believes in passionately innovating with customers to create a connected world. The award demonstrates our strength in being our customers’ reliable partner in creating enabling technology and solving challenges,” said Helen Zhang, Global General Manager, Interconnect Technologies for Dow Electronic Materials. “Our industry expertise, extensive global footprint, and speed to the market, are critical to deliver innovations with customers for tomorrow’s advances in electronics.”

Other new solutions the company will showcase at the Circuitex Suzhou Show include:

In Electrolytic Plating, Dow’s [Next Generation Thick Panel Copper Plating](#) has been developed to enhance throwing power for very thick panel plating (over 3.2 mm thickness). **The High Speed Direct Current Copper Plating Product** provides better throwing power at increased plating densities on high aspect ratio and microvia boards. **The Advanced Electrolytic Plating Tin** is designed to improve etching resistance capability and also improve surface uniformity with reduction in overall cost. All these products help to increase plating efficiency and deliver higher productivity without the need for customers to invest in additional equipment.

In Desmear, the new [CIRCUPOSIT™ Hole Prep 4126 Advanced Sweller](#) offers excellent cleaning performance for smear removal and creates outstanding surface texture that results in higher reliability electroless copper deposition. It provides cost-effective and sustainable benefits with optimized simple process and lower solvent concentration. The new Advanced Sweller is capable of handling both normal and high performance laminates with a wide operation window.



Dow Electronic Materials will be exhibiting in Booth #AW09 at the Circuitex Suzhou Show, which will be held at the Expo Plaza, Xiandai Avenue, Suzhou Industrial Park, from May 11 to 13, 2011.

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Dow Electronic Materials Research Fellow Martin Bayes (left) accepts the NPI award from PCD&F Magazine Editor Mike Buetow (right) on behalf of the company.

About Dow

Dow (NYSE: Dow) combines the power of science and technology with the "Human Element" to passionately innovate what is essential to human progress. The Company connects chemistry and innovation with the principles of sustainability to help address many of the world's most challenging problems such as the need for clean water, renewable energy generation and conservation, and increasing agricultural productivity. Dow's diversified industry-leading portfolio of specialty chemical, advanced materials, agrosiences and plastics businesses delivers a broad range of technology-based products and solutions to customers in approximately 160 countries and in high growth sectors such as electronics, water, energy, coatings and agriculture. In 2010, Dow had annual sales of \$53.7 billion and employed approximately 50,000 people worldwide. The Company's more than 5,000 products are manufactured at 188 sites in 35 countries across the globe. References to "Dow" or the "Company" mean The Dow Chemical Company and its consolidated subsidiaries unless otherwise expressly noted. More information about Dow can be found at www.dow.com.

About Dow Electronic Materials

Dow Electronic Materials, a global supplier of materials and technologies to the electronics industry, brings innovative leadership to the semiconductor, [interconnect](#), [finishing](#), [photovoltaic](#), display, LED and optics markets. From advanced technology centers worldwide, teams of talented Dow research scientists and application experts work closely with customers, providing solutions, products and technical service necessary for next-generation electronics. These partnerships energize Dow's power to invent. Its key end-use applications include a broad range of consumer electronics from personal computers, to television monitors, cellular phones, global positioning systems, automobile safety systems, and avionics.

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